Notification Number:	20220328004.0	Notification Date:	April 27, 2022
Title:	Datasheet for TFP401A-Q1		
Customer Contact:	PCN Manager	**Dept:**	Quality Services

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.

TEXAS INSTRUMENTS

TFP401A-Q1
SLDS190B – NOVEMBER 2012 – REVISED MARCH 2022

Changes from Revision A (January 2017) to Revision B (March 2022)   **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document.................1
- Added the Thermal Package information to the *Pin Functions* table...3
- Added *TFP401A-Q1* to the *Imax vs Input Frequency* figure... 11
- Added sentence to end of first paragraph that recommends soldering package thermal pad to PCB in order to minimize stress on peripheral pins.. 26

The datasheet number will be changing.

Device Family	Change From:	Change To:
TFP401A-Q1	SLDS190A	SLDS190B

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/TFP401A-Q1

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:

TFP401AIPZPRQ1			

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN_ww_admin_team@list.ti.com

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